

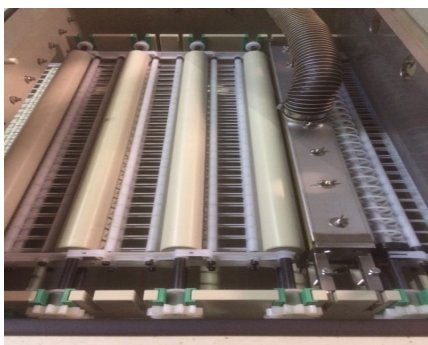
CHEM CLEAN

Wise Chemstar 650 microetch

August 2014

Creating the proper Copper surface topography, removal of oxidation and cleanliness is an important aspect of PCB fabrication to promote optimal adhesion for dry film, soldermask and plating. Mechanical scrubbing can lead to material distortion, especially on thin cores, flex and Teflon materials. Vertical dip is not as efficient or reliable for cleaning small holes and tight features. To address this need, Netvia Group has purchased and installed a new horizontal chemical clean line, capable of processing thin cores (down to 2 mils thickness). This addition further demonstrates our initiative to continuously improve, build high reliability and complex printed circuit boards.

Should you have any questions about how we can help you, do not hesitate to let us know.



Key Features

- Optimal surface topography of Copper
- Excellent promotion of adhesion prior to soldermask, dry film and plating operations
- Auto dosing of chemistry with adjustable impingement
- 2 mil microvias / 6 mil through vias
- Thin core transport / down to 2 mils
- Touch screen control
- Stand-by with auto start / stop function
- Quick disconnect of spray bars for ease of maintenance